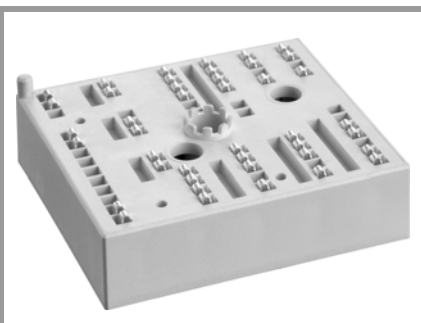


SKiiP 25AC12T4V25



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SKiiP 25AC12T4V25

Features*

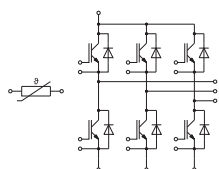
- Trench 4 IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

Typical Applications

- Inverter up to 26 kVA
- Typical motor power 15 kW

Remarks

- V_{CEsat} , V_F = chip level value
- Case temp. limited to $T_C = 125^\circ\text{C}$ max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)
- Dynamic test results for $V_{CC} = 600\text{V}$, $R_{Gon/off} = 12\Omega$, $I_C = 50\text{A}$, $V_{GE} = \pm 15\text{V}$: $E_{on} = 5.6\text{mJ}$, $E_{off} = 6.1\text{mJ}$, $E_{rr} = 3.3\text{mJ}$, $di/dt_{on} = 1440\text{A}/\mu\text{s}$, $t_{don} = 58\text{ns}$, $t_r = 43\text{ns}$, $di/dt_{off} = 600\text{A}/\mu\text{s}$, $t_{doff} = 370\text{ns}$, $t_f = 65\text{ns}$



AC

Absolute Maximum Ratings

Symbol	Conditions	Values	Unit	
Inverter - IGBT				
V_{CES}	$T_j = 25^\circ\text{C}$	1200	V	
I_C	$\lambda_{paste}=0.8\text{ W}/(\text{mK})$	$T_s = 25^\circ\text{C}$	68	A
	$T_j = 175^\circ\text{C}$	$T_s = 70^\circ\text{C}$	55	A
I_C	$\lambda_{paste}=2.5\text{ W}/(\text{mK})$	$T_s = 25^\circ\text{C}$	t.b.d.	A
	$T_j = 175^\circ\text{C}$	$T_s = 70^\circ\text{C}$	t.b.d.	A
I_{Cnom}		50	A	
I_{CRM}		150	A	
V_{GES}		-20 ... 20	V	
t_{psc}	$V_{CC} = 800\text{ V}$ $V_{GE} \leq 15\text{ V}$ $V_{CES} \leq 1200\text{ V}$	$T_j = 150^\circ\text{C}$	10	μs
T_j		-40 ... 175	$^\circ\text{C}$	
Inverse - Diode				
V_{RRM}	$T_j = 25^\circ\text{C}$	1200	V	
I_F	$\lambda_{paste}=0.8\text{ W}/(\text{mK})$	$T_s = 25^\circ\text{C}$	60	A
	$T_j = 175^\circ\text{C}$	$T_s = 70^\circ\text{C}$	48	A
I_F	$\lambda_{paste}=2.5\text{ W}/(\text{mK})$	$T_s = 25^\circ\text{C}$	t.b.d.	A
	$T_j = 175^\circ\text{C}$	$T_s = 70^\circ\text{C}$	t.b.d.	A
I_{FRM}		100	A	
I_{FSM}	$t_p = 10\text{ ms}$, $\sin 180^\circ$, $T_j = 150^\circ\text{C}$	270	A	
T_j		-40 ... 175	$^\circ\text{C}$	
Module				
$I_t(\text{RMS})$	$T_{terminal} = 80^\circ\text{C}$, 20 A per spring	60	A	
T_{stg}	module without TIM	-40 ... 125	$^\circ\text{C}$	
V_{isol}	AC sinus 50 Hz, $t = 1\text{ min}$	2500	V	

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
Inverter - IGBT					
$V_{CE(sat)}$	$I_C = 50\text{ A}$ $V_{GE} = 15\text{ V}$ chiplevel	$T_j = 25^\circ\text{C}$	1.85	2.10	V
		$T_j = 150^\circ\text{C}$	2.20	2.40	V
V_{CE0}	chiplevel	$T_j = 25^\circ\text{C}$	0.80	0.90	V
		$T_j = 150^\circ\text{C}$	0.70	0.80	V
r_{CE}	$V_{GE} = 15\text{ V}$ chiplevel	$T_j = 25^\circ\text{C}$	21	24	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	30	32	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 1.7\text{ mA}$	5	5.8	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = 1200\text{ V}$, $T_j = 25^\circ\text{C}$			1	mA
C_{ies}	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	2.77		nF
C_{oes}		$f = 1\text{ MHz}$	0.21		nF
C_{res}		$f = 1\text{ MHz}$	0.16		nF
Q_G	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		283		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		4.0		Ω
$t_{d(on)}$	$V_{CC} = 800\text{ V}$	$T_j = 150^\circ\text{C}$	45		ns
t_r	$I_C = 22\text{ A}$ $R_{Gon} = 12\Omega$	$T_j = 150^\circ\text{C}$	19		ns
		$T_j = 150^\circ\text{C}$	3.4		mJ
E_{on}	$R_{Goff} = 1\Omega$	$T_j = 150^\circ\text{C}$	3.4		mJ
$t_{d(off)}$	$di/dt_{on} = 1640\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	480		ns
t_f	$di/dt_{off} = 320\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	44		ns
E_{off}	$V_{GE} = +15/0\text{ V}$	$T_j = 150^\circ\text{C}$	3.1		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=0.8\text{ W}/(\text{mK})$		0.71		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste}=2.5\text{ W}/(\text{mK})$		t.b.d.		K/W

SKiiP 25AC12T4V25



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Features*

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- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

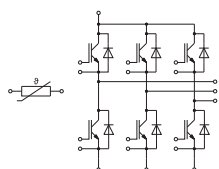
Typical Applications

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- Typical motor power 15 kW

Remarks

- V_{CEsat} , V_F = chip level value
- Case temp. limited to $T_C = 125^\circ\text{C}$ max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)
- Dynamic test results for $V_{CC} = 600\text{V}$, $R_{Gon/off} = 12\Omega$, $I_c = 50\text{A}$, $V_{GE} = \pm 15\text{V}$: $E_{on} = 5.6\text{mJ}$, $E_{off} = 6.1\text{mJ}$, $E_{rr} = 3.3\text{mJ}$, $di/dt_{on} = 1440\text{A}/\mu\text{s}$, $t_{don} = 58\text{ns}$, $t_r = 43\text{ns}$, $di/dt_{off} = 600\text{A}/\mu\text{s}$, $t_{doff} = 370\text{ns}$, $t_f = 65\text{ns}$

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse - Diode						
$V_F = V_{EC}$	$I_F = 50\text{ A}$ $V_{GE} = 0\text{ V}$ chipllevel	$T_j = 25^\circ\text{C}$		2.22	2.54	V
		$T_j = 150^\circ\text{C}$		2.18	2.50	V
V_{F0}	chipllevel	$T_j = 25^\circ\text{C}$		1.30	1.50	V
		$T_j = 150^\circ\text{C}$		0.90	1.10	V
r_F	chipllevel	$T_j = 25^\circ\text{C}$		18	21	m Ω
		$T_j = 150^\circ\text{C}$		26	28	m Ω
I_{RRM}	$I_F = 22\text{ A}$	$T_j = 150^\circ\text{C}$		0		A
Q_{rr}	$di/dt_{off} = 1680\text{ A}/\mu\text{s}$ $V_{GE} = +15/0\text{ V}$	$T_j = 150^\circ\text{C}$		5.5		μC
E_{rr}	$V_{CC} = 800\text{ V}$	$T_j = 150^\circ\text{C}$		2.9		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 0.8\text{ W}/(\text{mK})$			0.95		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 2.5\text{ W}/(\text{mK})$			t.b.d.		K/W
Module						
L_{CE}				-		nH
M_s	to heat sink		2		2.5	Nm
w				55		g
Temperature Sensor						
R_{100}	$T_r = 100^\circ\text{C}$ ($R_{25} = 1000\Omega$)			$1670 \pm 3\%$		Ω
$R_{(T)}$	$R_{(T)} = 1000\Omega [1 + A(T - 25^\circ\text{C}) + B(T - 25^\circ\text{C})^2]$, $A = 7.635 \cdot 10^{-3} \text{ }^\circ\text{C}^{-1}$, $B = 1.731 \cdot 10^{-5} \text{ }^\circ\text{C}^{-2}$					



AC

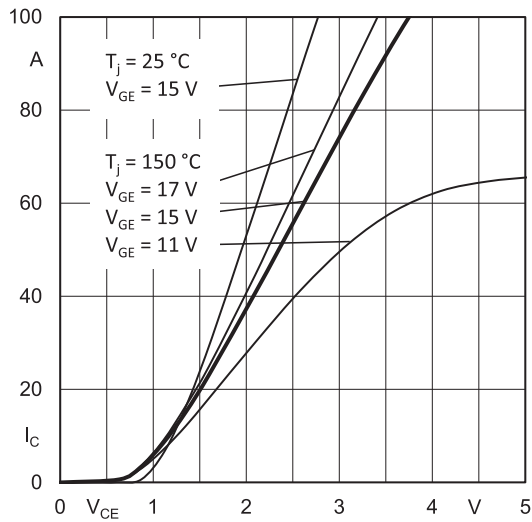


Fig. 1: Typ. output characteristic

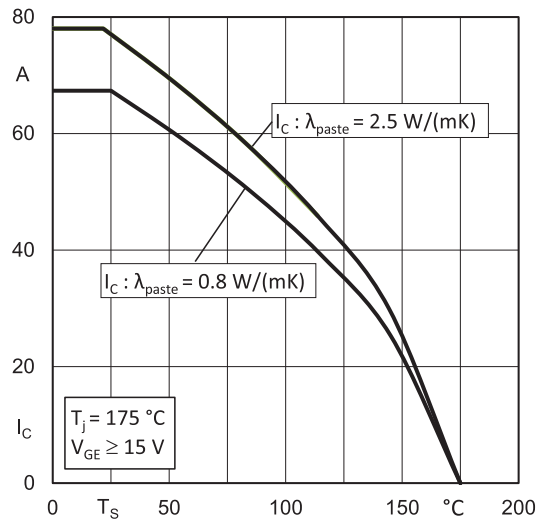


Fig. 2: Rated current vs. temperature $I_C = f(T_S)$

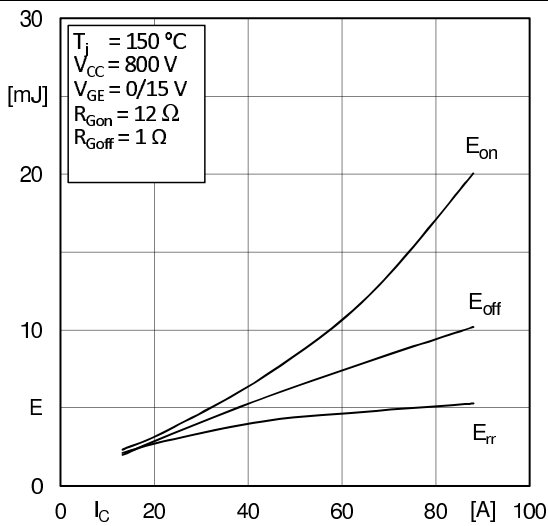


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

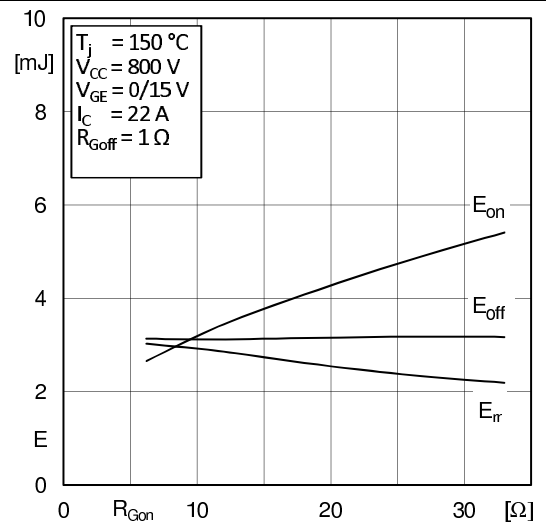


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

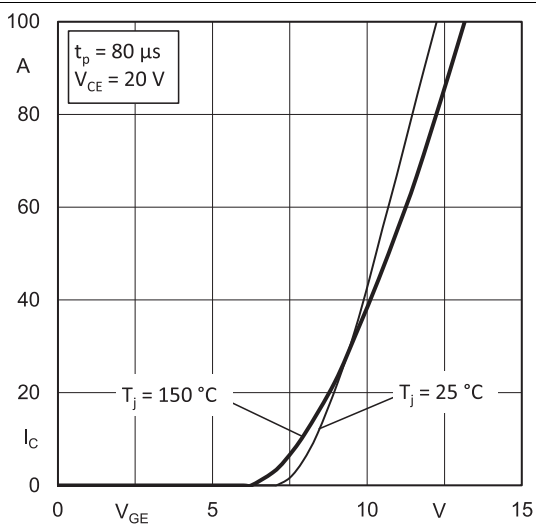


Fig. 5: Typ. transfer characteristic

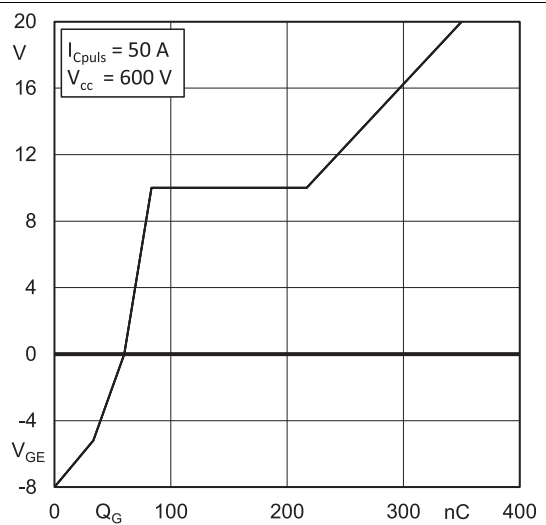


Fig. 6: Typ. gate charge characteristic

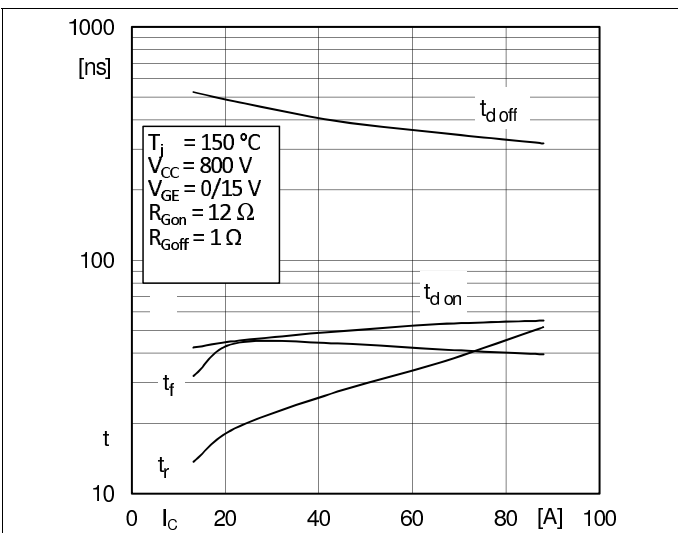


Fig. 7: Typ. switching times vs. I_C

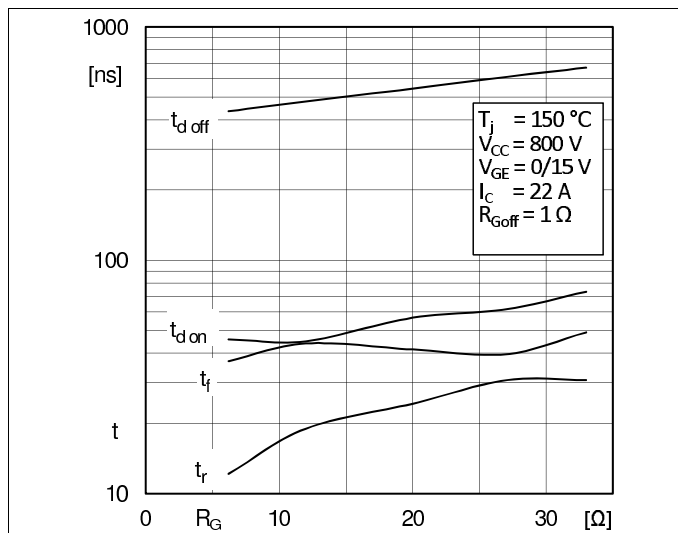


Fig. 8: Typ. switching times vs. gate resistor R_G

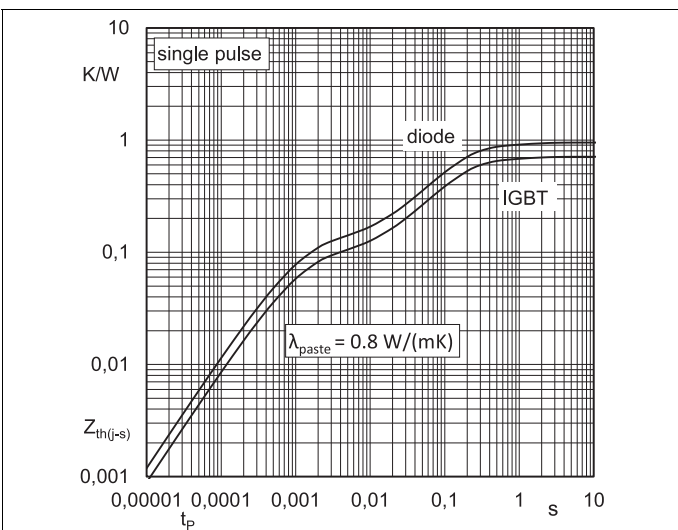


Fig. 9: Typ. transient thermal impedance

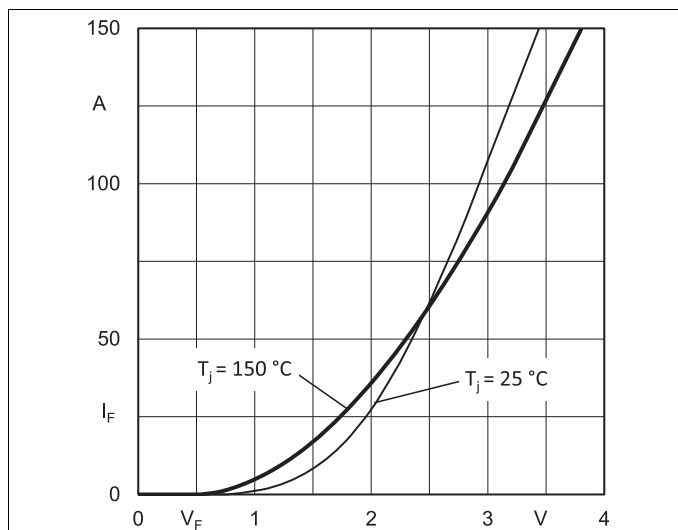


Fig. 10: Typ. CAL diode forward characteristic

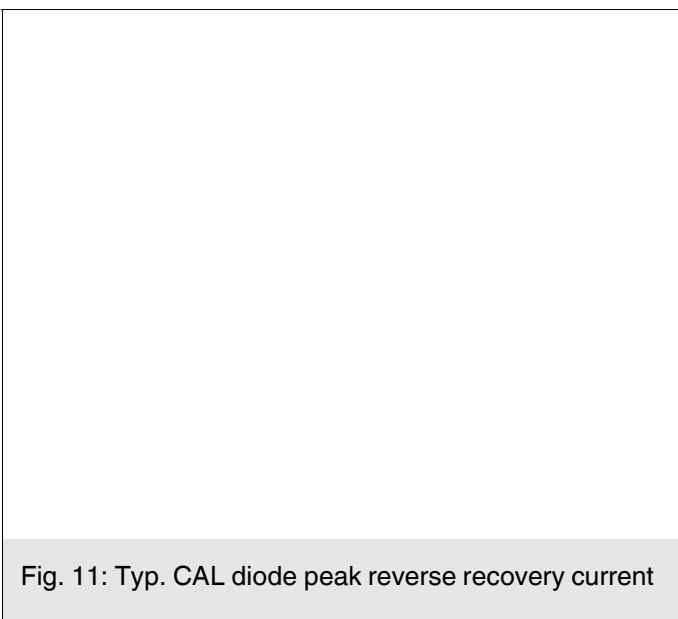


Fig. 11: Typ. CAL diode peak reverse recovery current

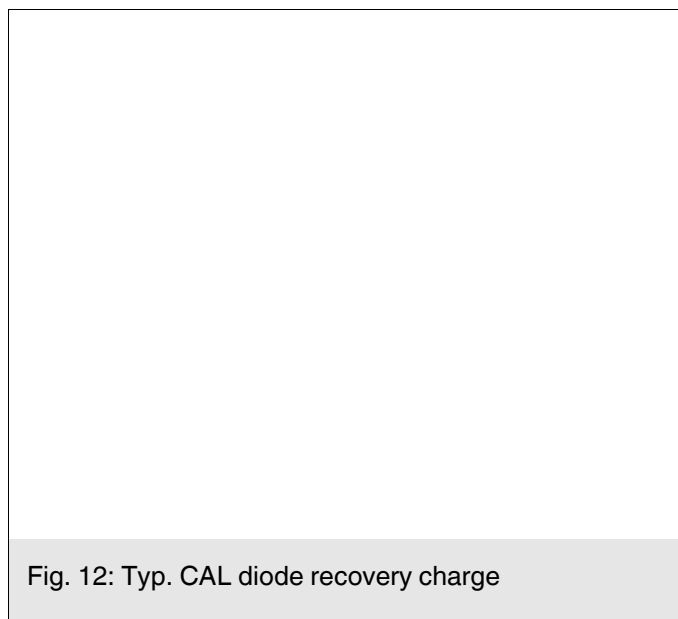
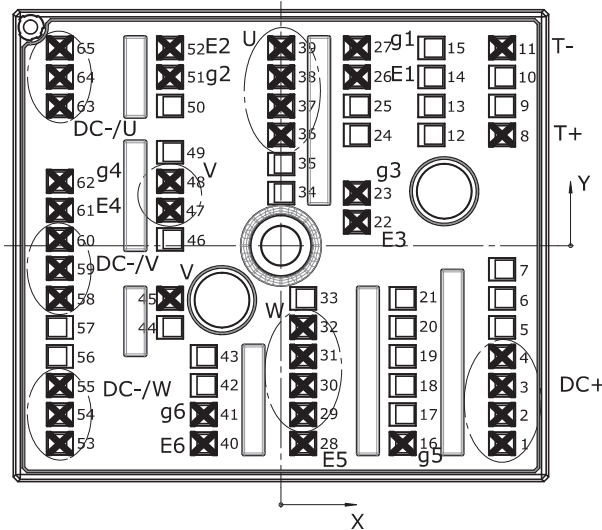


Fig. 12: Typ. CAL diode recovery charge

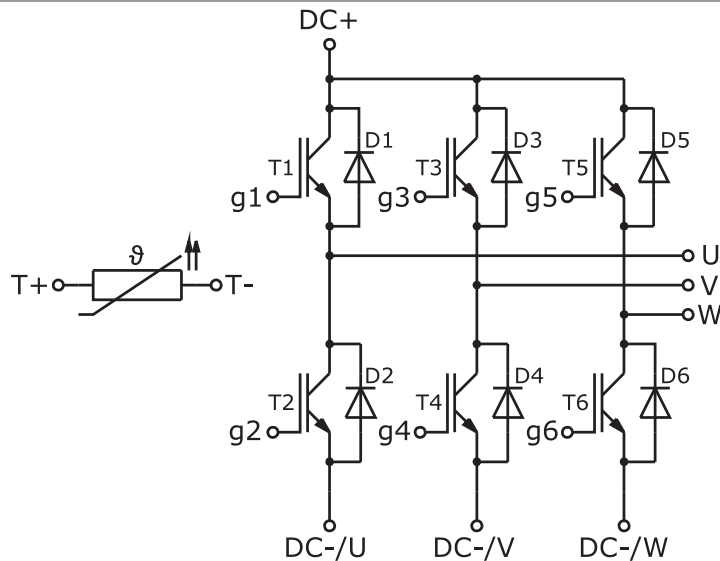
SKiP 25AC12T4V25

Pin out											
Pin	X	Y	Function	Pin	X	Y	Function	Pin	X	Y	Function
1	24,38	-21,80	DC+	23	8,38	5,80	g3	45	-12,23	-5,80	V
2	24,38	-18,60	DC+	24	8,38	12,20		46	-12,23	0,70	
3	24,38	-15,40	DC+	25	8,38	15,40		47	-12,23	3,90	V
4	24,38	-12,20	DC+	26	8,38	18,60	E1	48	-12,23	7,10	V
5	24,38	-9,00		27	8,38	21,80	g1	49	-12,23	10,30	
6	24,38	-5,80		28	2,46	-21,80	E5	50	-12,23	15,40	
7	24,38	-2,60		29	2,46	-18,60	W	51	-12,23	18,60	g2
8	24,38	12,20	T+	30	2,46	-15,40	W	52	-12,23	21,80	E2
9	24,38	15,40		31	2,46	-12,20	W	53	-24,38	-21,80	DC-/W
10	24,38	18,60		32	2,46	-9,00	W	54	-24,38	-18,60	DC-/W
11	24,38	21,80	T-	33	2,46	-5,80		55	-24,38	-15,40	DC-/W
12	16,58	12,20		34	0,03	5,80		56	-24,38	-12,20	
13	16,58	15,40		35	0,03	9,00		57	-24,38	-9,00	
14	16,58	18,60		36	0,03	12,20	U	58	-24,38	-5,80	DC-/V
15	16,58	21,80		37	0,03	15,40	U	59	-24,38	-2,50	DC-/V
16	13,42	-21,80	g5	38	0,03	18,60	U	60	-24,38	0,70	DC-/V
17	13,42	-18,60		39	0,03	21,80	U	61	-24,38	3,90	E4
18	13,42	-15,40		40	-8,51	-21,80	E6	62	-24,38	7,10	g4
19	13,42	-12,20		41	-8,51	-18,60	g6	63	-24,38	15,40	DC-/U
20	13,42	-9,00		42	-8,51	-15,40		64	-24,38	18,60	DC-/U
21	13,42	-5,80		43	-8,51	-12,20		65	-24,38	21,80	DC-/U
22	8,38	2,60	E3	44	-12,23	-9,00					

all values in mm



Pinout and Dimensions



Pinout

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

***IMPORTANT INFORMATION AND WARNINGS**

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